PCN Number:	20180717010		PCN Date:	July 18, 2018
Title:	Datasheet for TLV3201-Q1, TLV3202-Q1			
Customer Contact:	PCN Manager		Dept:	Quality Services

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.

TEXAS INSTRUMENTS

TLV3201-Q1, TLV3202-Q1
SBOS856A – FEBRUARY 2017 – REVISED DECEMBER 2017

Changes from Original (February 2017) to Revision A   Page

· Changed figure 29 15

The datasheet number will be changing.

Device Family	Change From:	Change To:
TLV3201-Q1, TLV3202-Q1	SBOS584D	SBOS584E

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/TLV3201-Q1

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TLV3201AQDCKRQ1	TLV3202AQDGKRQ1		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com